



4. Describe with suitable diagrams. The operation of a CCD. 5
5. With energy band diagram, describe Schottky junction barrier formation. Describe its operation under external bias. 3 + 2
6. Explain with block diagram, the punch through effect of a submicron MOS transistor. Explain the advantages of using an IGBT in place of a BJT. 3 + 2

GROUP - C

(Long Answer Type Questions)

Answer any three questions. 3 × 15 = 45

7. What do you mean by Thyristors ? Discuss the characteristic of Power MOSFETs. Sketch the cross-section of VMOS Power MOSFET structure and describe its operation. 2 + 3 + 10
8. What are Bulk micromachining and Surface micromachining ? Describe each with schematic diagrams. 5 + 10
9. Explain how we can design a high electron mobility system using heterojunction. What are the advantages of high electron mobility system ? What do you mean Ballistic transport ? 6 + 4 + 5
10. What do you mean by luminescence process ? How does a LED work ? Show the construction of typical LED. What are the applications of LED ? 3 + 5 + 5 + 2
11. Discuss the I-V characteristics of the MOSFET when biased in non-saturation and saturation regions.

To design the width of a MOSFET such that a specified current is induced for a given applied bias, consider an ideal n-channel MOSFET with parameters $L = 1.25 \mu\text{m}$, $\mu_n = 650 \text{ cm}^2 / \text{V-S}$, $C_{ox} = 6.9 \times 10^{-8} \text{ F/cm}^2$ and $V_T = 0.65 \text{ V}$. Design the channel width W such that $I_D (\text{sat}) = 4 \text{ mA}$ for $V_{GS} = 5\text{V}$. 9 + 6

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